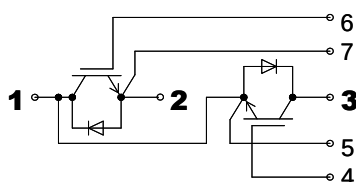


# SGG50NF120UC1

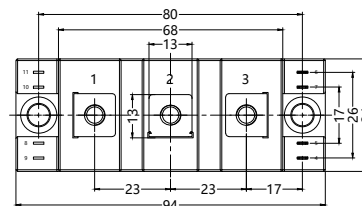
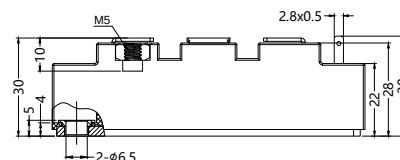
## IGBT Modules



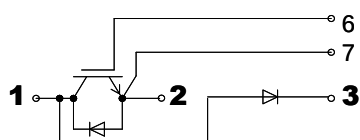
SGG50NF120UC1



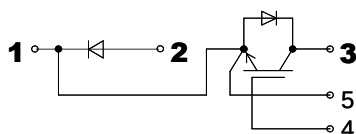
Dimensions in mm (1mm = 0.0394")



SGD50NF120UC1



SDG50NF120UC1



$T_C = 25^{\circ}\text{C}$ , unless otherwise specified

| Symbol        | Conditions                                                            | Values           | Units              |
|---------------|-----------------------------------------------------------------------|------------------|--------------------|
| IGBT          |                                                                       |                  |                    |
| $V_{CES}$     |                                                                       | 1200             | V                  |
| $I_C$         | $T_C = 25(100)^{\circ}\text{C}$                                       | 100(50)          | A                  |
| $I_{CRM}$     | $T_C = 25^{\circ}\text{C}$ , $t_P = 1\text{ms}$                       | 200              | A                  |
| $V_{GES}$     |                                                                       | $\pm 20$         | V                  |
| $T_{vj}$      |                                                                       | $-40 \dots +175$ | $^{\circ}\text{C}$ |
| Inverse Diode |                                                                       |                  |                    |
| $I_F = -I_C$  | $T_C = 25(80)^{\circ}\text{C}$                                        | 40(20)           | A                  |
| $I_{FRM}$     | $T_C = 25^{\circ}\text{C}$ , $t_P = 1\text{ms}$                       | 60               | A                  |
| $I_{FSM}$     | $t_P = 10\text{ms}$ ; $\sin 180^{\circ}$ ; $T_J = 25^{\circ}\text{C}$ | 90               | A                  |
| $V_{RRM}$     |                                                                       | 1200             | V                  |
| Module        |                                                                       |                  |                    |
| $I_{t(RMS)}$  | $T_{\text{terminal}} = 80^{\circ}\text{C}$                            | 100              | A                  |
| $T_{stg}$     |                                                                       | $-40 \sim 125$   | $^{\circ}\text{C}$ |
| $V_{isol}$    | AC, 1min                                                              | 2500             | V                  |

### Features

- Planar Field Stop technology
- Low switching losses
- Switching frequency up to 20kHz
- Square RBSOA, no latch up
- High short circuit capability
- Positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- Soft switching diode Technology
- Package with copper base plate
- Isolation voltage 4000 V

### Application

- Inverter Machines

### Advantages

- space and weight savings
- reduced protection circuits

# SGG50NF120UC1

## IGBT Modules

### Characteristics

$T_C = 25^{\circ}\text{C}$ , unless otherwise specified

| Symbol                                           | Conditions                                                             | min. | typ.        | max.     | Units         |
|--------------------------------------------------|------------------------------------------------------------------------|------|-------------|----------|---------------|
| <b>IGBT</b>                                      |                                                                        |      |             |          |               |
| $V_{GE(th)}$                                     | $V_{GE} = V_{CE}$ , $I_C = 3\text{mA}$                                 | 5.0  | 6.0         | 6.8      | V             |
| $I_{CES}$                                        | $V_{GE} = 0$ ; $V_{CE} = V_{CES}$ ; $T_J = 25^{\circ}\text{C}$         |      |             | 1.0      | mA            |
| $V_{CE(TO)}$                                     | $T_J = 25^{\circ}\text{C}$                                             |      | 0.8         | 0.9      | V             |
| $r_{CE}$                                         | $V_{GE} = 15\text{V}$ , $T_J = 25(150)^{\circ}\text{C}$                |      | 14.0(21)    | 16(22)   | m $\Omega$    |
| $V_{CE(sat)}$                                    | $I_C = 50\text{A}$ ; $V_{GE} = 15\text{V}$ ; chip level                |      | 2.10        | 2.30     | V             |
| $C_{ies}$                                        | under following conditions                                             |      | 4.8         |          | nF            |
| $C_{oes}$                                        | $V_{GE} = 0$ , $V_{CE} = 25\text{V}$ , $f = 1\text{MHz}$               |      | 0.27        |          |               |
| $C_{res}$                                        |                                                                        |      | 0.14        |          |               |
| $L_{CE}$                                         |                                                                        |      |             | 30       | nH            |
| $R_{CC'+EE'}$                                    | res., terminal-chip $T_C = 25(125)^{\circ}\text{C}$                    |      | 0.65(1.09)  |          | m $\Omega$    |
| $t_{d(on)}$                                      | under following conditions:                                            |      | 58          |          | ns            |
| $t_r$                                            | $V_{CC} = 600\text{V}$ , $I_C = 50\text{A}$                            |      | 49          |          | ns            |
| $t_{d(off)}$                                     | $R_{Gon} = R_{Goff} = 1\Omega$ , $T_J = 150^{\circ}\text{C}$           |      | 295         |          | ns            |
| $t_f$                                            | $V_{GE} = \pm 15\text{V}$                                              |      | 40          |          | ns            |
| $E_{on}/E_{off}/E_{ts}$                          |                                                                        |      | 4.3/2.4/6.7 |          | mJ            |
| <b>Inverse Diode</b> under following conditions: |                                                                        |      |             |          |               |
| $V_F = V_{EC}$                                   | $I_F = 50\text{A}$ ; $V_{GE} = 0\text{V}$ ; $T_J = 25^{\circ}\text{C}$ |      | 1.90        | 2.54     | V             |
| $V_{(FO)}$                                       | $T_J = 25(150)^{\circ}\text{C}$                                        |      | 1.3(0.90)   | 1.5(1.1) | V             |
| $r_F$                                            | $T_J = 25(150)^{\circ}\text{C}$                                        |      | 18(25)      | (20)     | m $\Omega$    |
| $I_{RM}$                                         | $I_F = 50\text{A}$ ; $T_J = 150^{\circ}\text{C}$                       |      | 5.4         |          | A             |
| $Q_{rr}$                                         | $di/dt = 100\text{A}/\mu\text{s}$                                      |      | 0.15        |          | $\mu\text{C}$ |
| $E_{rr}$                                         | $V_{GE} = \pm 15\text{V}$                                              |      | 3.8         |          | mJ            |
| <b>Thermal Characteristics</b>                   |                                                                        |      |             |          |               |
| $R_{th(j-c)}$                                    | per IGBT                                                               |      |             | 0.45     | K/W           |
| $R_{th(j-c)D}$                                   | per Inverse Diode                                                      |      |             | 1.20     | K/W           |
| $R_{th(c-s)}$                                    | per module                                                             |      |             | 0.33     | K/W           |
| <b>Mechanical Data</b>                           |                                                                        |      |             |          |               |
| $M_s$                                            | to heatsink M5                                                         | 3    |             | 5        | Nm            |
| $M_t$                                            | to terminals M5                                                        | 2.5  |             | 5        | Nm            |
| Weight                                           | typical                                                                |      |             | 160      | g             |



# SGG50NF120UC1

## IGBT Modules

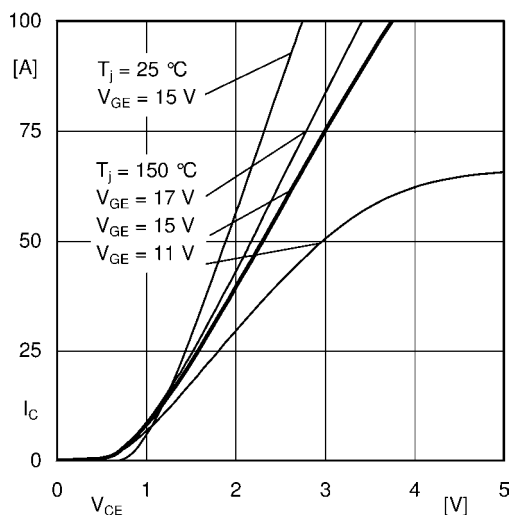


Fig. 1: Typ. output characteristic, inclusive  $R_{CC} + EE$

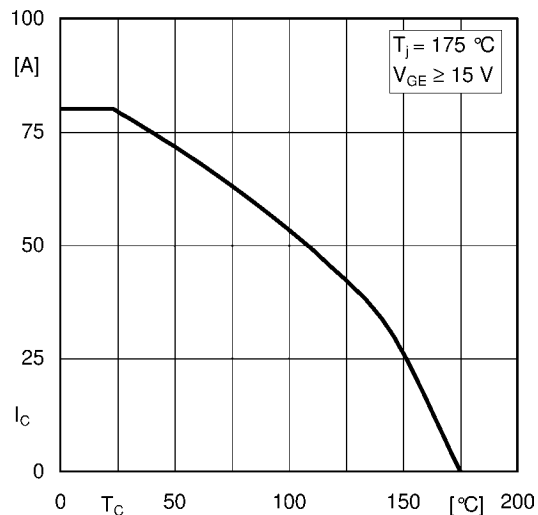


Fig. 2: Rated current vs. temperature  $I_C = f(T_C)$

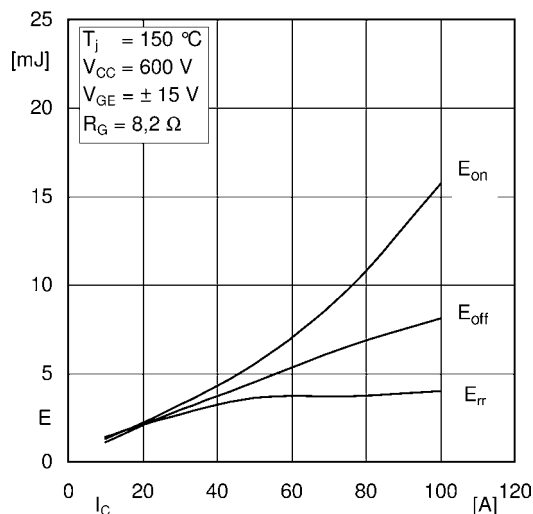


Fig. 3: Typ. turn-on /-off energy =  $f(I_C)$

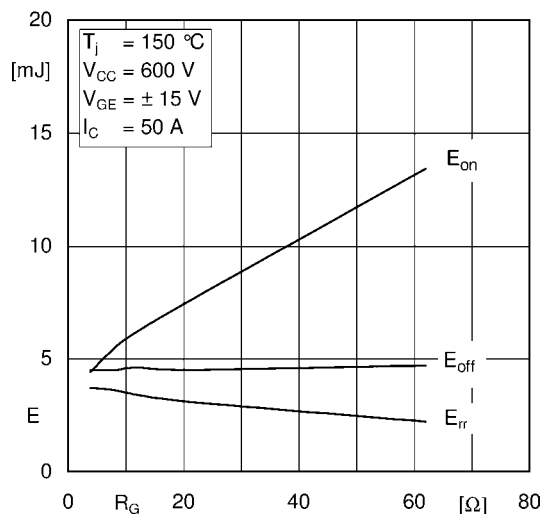
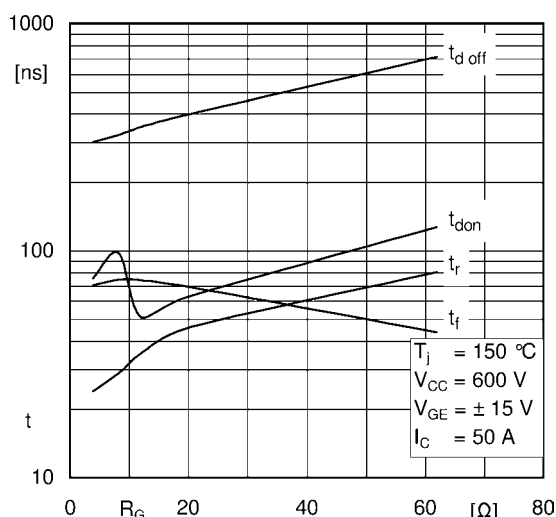
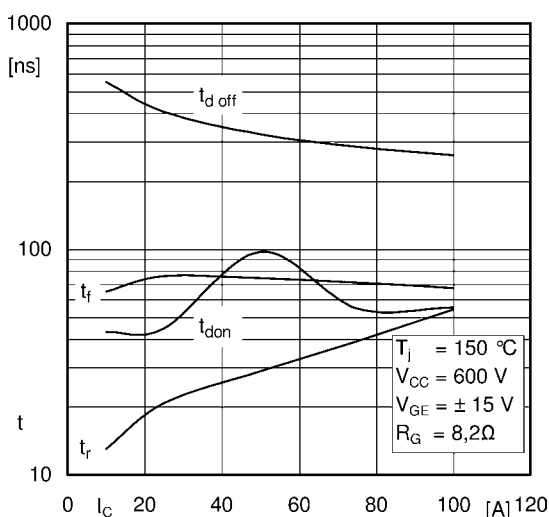
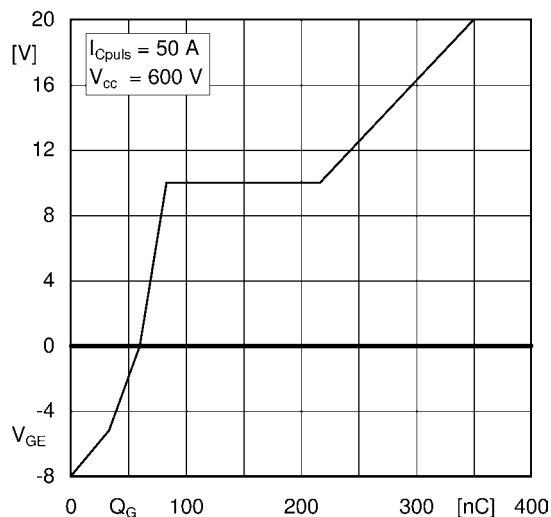
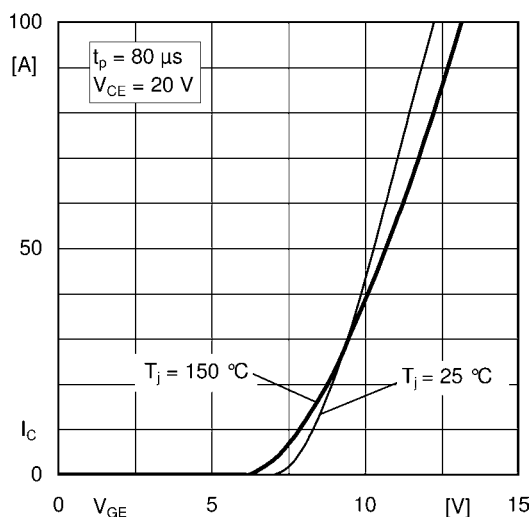


Fig. 4: Typ. turn-on /-off energy =  $f(R_G)$

# SGG50NF120UC1

## IGBT Modules



# SGG50NF120UC1

## IGBT Modules

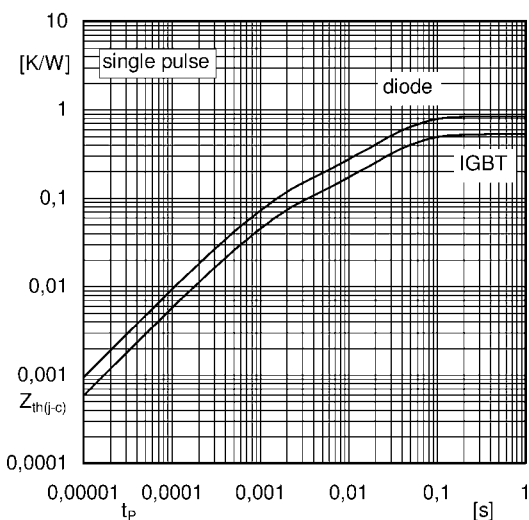


Fig. 9: Transient thermal impedance

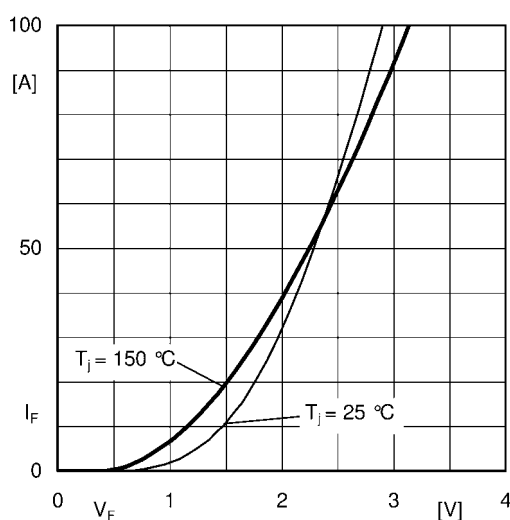


Fig. 10: Typ. FRD diode forward charact., incl.  $R_{CC'+EE'}$

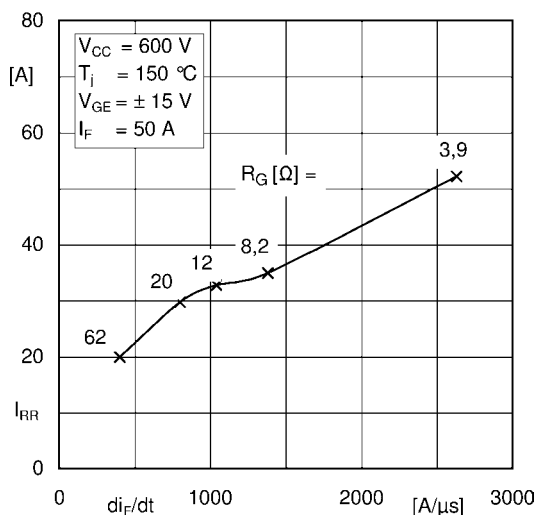


Fig. 11: FRD diode peak reverse recovery current

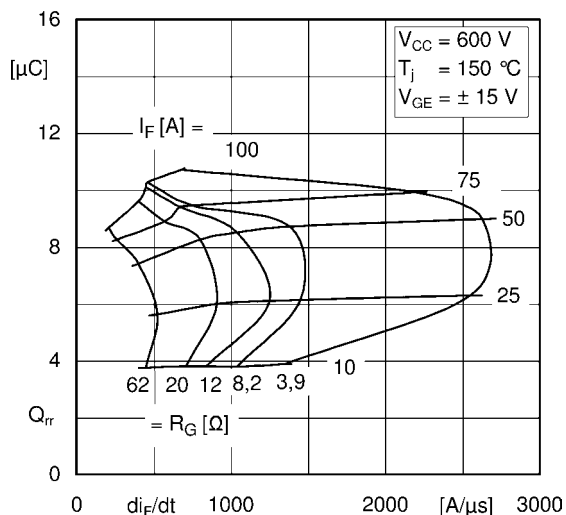


Fig. 12: Typ. FRD diode peak reverse recovery charge

# SGG50NF120UC1

## IGBT Modules

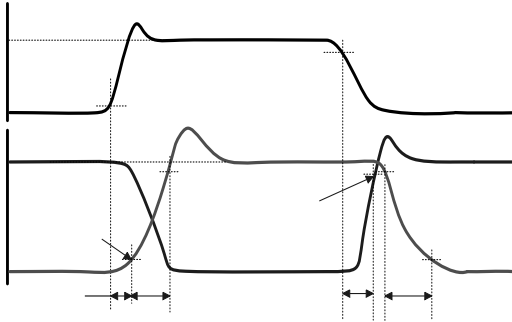


Figure 13. Definition of switching times

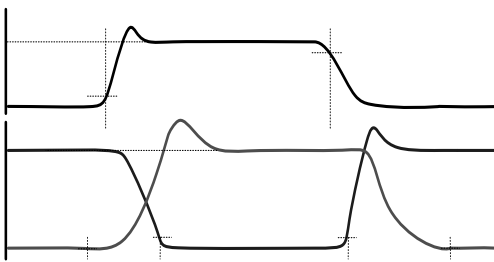


Figure 14. Definition of switching losses

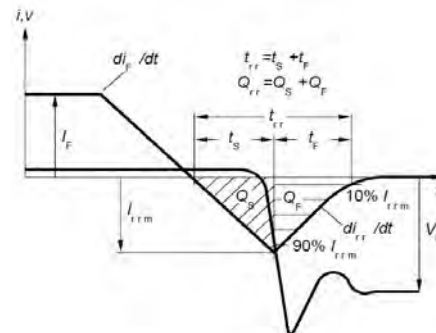


Figure 15. Definition of diodes switching characteristics

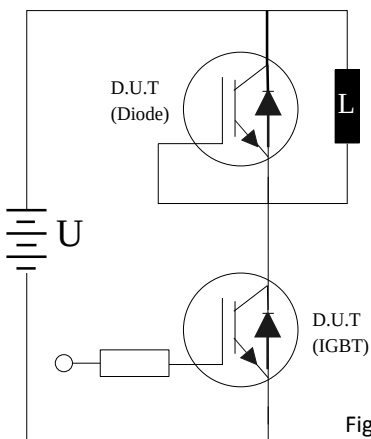


Figure 16. Dynamic test circuit